



Ipoh

KEY SERVICES

- Wafer probe and Bump Probe
- Wafer Backgrinding/Polishing
- Assembly of Leadframe, Array and Leadless packages
- Final Test
- Tape and Reel
- WLCSP/WLBGA Services
- Drop Shipping and Distribution

KEY FACTS

- Factory Floor Space Services: 550,000 ft² (51,000 m²)
- Equipment Capacity: 13 million units/capacity a day
- Employees: 3,600

SUPPLIER AWARDS

- Skyworks, Power Integrations, Triquint and Mindspeed

TEST PLATFORMS

- Linear/Analog
- High-end RF
- Mixed Signal
- VLSI

PACKAGE PORTFOLIO

- Array Packages - MCM/SIP, LGA, FC-LGA
- Leadframe Packages - SOIC, QSOP, SOT23, TSOT23, MSOP, TSSOP, SC70, Micro P
- Leadless Packages - SLP, FC-SLP, DFN/QFN, WLCSP
- Module SLP/LGA Packages
- MIS Package Technology

CERTIFICATIONS

- ISO/TS16949:2009
- ISO9001:2008
- ISO14001:2004
- Certificate of Green Partner (Sony)
- Samsung ECO Partner
- EICC VAP

